



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20251216001.2

**Qualification of TI Clark as an additional Probe Test site and
Assembly/Test site for select devices
Change Notification / Sample Request**

Date: December 17, 2025

To: Mouser PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Change Management Team
SC Business Services

20251216001.2
Attachment

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS62872Y2QWRXSRQ1	NULL
TPS62872Y4QWRXSRQ1	NULL
TPS62870Y0QWRXSRQ1	NULL
TPS62872N2QWRXSRQ1	NULL
TPS62872N3QWRXSRQ1	NULL
TPS62872Y7QWRXSRQ1	NULL
TPS62872N0QWRXSRQ1	NULL
TPS62873N1QWRXSRQ1	NULL
TPS62871Y1QWRXSRQ1	NULL
TPS62873Y1QWRXSRQ1	NULL
TPS62871Y5QWRXSRQ1	NULL
TPS62871QWRXSRQ1	NULL
TPS62870Y1QWRXSRQ1	NULL
TPS62871N1QWRXSRQ1	NULL
TPS62871N0QWRXSRQ1	NULL
TPS62873N0QWRXSRQ1	NULL
TPS62870Y2QWRXSRQ1	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20251216001.2	PCN Date:	December 17, 2025
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Title:	Qualification of TI Clark as an additional Probe Test site and Assembly/Test site for select devices
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Customer Contact:	Change Management Team	Dept:	Quality Services
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Proposed 1st Ship Date:	June 15, 2026	Sample requests accepted until:	February 15, 2026*
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***Sample requests received after February 15, 2026 will not be supported.**

Change Type:			
<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/> Wafer Bump Material
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/>	Data Sheet	<input type="checkbox"/> Wafer Bump Process
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/> Wafer Fab Site
<input type="checkbox"/> Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/> Wafer Fab Material
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/> Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of TI Clark as an additional probe test site and Assembly/Test site for the device listed below. Material differences between sites as follows.

	Current Site	Additional site
Assembly/Test site	CARZ	TI Clark
Mold compound	SID#445988	4223495
Probe Test site	CD-PR	CLARK-PR

Qual details are provided in the Qual Data Section.

Test coverage, insertions, conditions will remain consistent with current testing.

Reason for Change:

Supply continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

Review the standard data packet (SDP) for comparison.

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change			

Changes to product identification resulting from this PCN:

Assembly Site Information:

Assembly Site	Assembly Site Origin Code (22L)	Assembly Site Country Code (23L)	Assembly Site City
CARZ	CSZ	CHN	Jiangsu
TI Clark	QAB	PHL	Angeles City, Pampanga

Sample product shipping label (not actual product label):

 TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 29 MSL 2 / 260C / 1 YEAR MSL 1 / 235C / UNLIM OPT: ITEM: 39 LBL: 5A (L)T0:1750		 	(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY(1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21L) CCO:USA (22L) AS0: MLA (23L) AC0: MYS																									
Product Affected <table border="1"> <tr><td>TPS62870N0QWRXSRQ1</td><td>TPS62871QWRXSRQ1</td><td>TPS62872Y2QWRXSRQ1</td></tr> <tr><td>TPS62870QWRXSRQ1</td><td>TPS62871Y1QWRXSRQ1</td><td>TPS62872Y4QWRXSRQ1</td></tr> <tr><td>TPS62870Y0QWRXSRQ1</td><td>TPS62871Y5QWRXSRQ1</td><td>TPS62872Y7QWRXSRQ1</td></tr> <tr><td>TPS62870Y1QWRXSRQ1</td><td>TPS62872N0QWRXSRQ1</td><td>TPS62873N0QWRXSRQ1</td></tr> <tr><td>TPS62870Y2QWRXSRQ1</td><td>TPS62872N2QWRXSRQ1</td><td>TPS62873N1QWRXSRQ1</td></tr> <tr><td>TPS62870Y3QWRXSRQ1</td><td>TPS62872N3QWRXSRQ1</td><td>TPS62873QWRXSRQ1</td></tr> <tr><td>TPS62871N0QWRXSRQ1</td><td>TPS62872QWRXSRQ1</td><td>TPS62873Y1QWRXSRQ1</td></tr> <tr><td>TPS62871N1QWRXSRQ1</td><td>TPS62872Y1QWRXSRQ1</td><td></td></tr> </table>					TPS62870N0QWRXSRQ1	TPS62871QWRXSRQ1	TPS62872Y2QWRXSRQ1	TPS62870QWRXSRQ1	TPS62871Y1QWRXSRQ1	TPS62872Y4QWRXSRQ1	TPS62870Y0QWRXSRQ1	TPS62871Y5QWRXSRQ1	TPS62872Y7QWRXSRQ1	TPS62870Y1QWRXSRQ1	TPS62872N0QWRXSRQ1	TPS62873N0QWRXSRQ1	TPS62870Y2QWRXSRQ1	TPS62872N2QWRXSRQ1	TPS62873N1QWRXSRQ1	TPS62870Y3QWRXSRQ1	TPS62872N3QWRXSRQ1	TPS62873QWRXSRQ1	TPS62871N0QWRXSRQ1	TPS62872QWRXSRQ1	TPS62873Y1QWRXSRQ1	TPS62871N1QWRXSRQ1	TPS62872Y1QWRXSRQ1	
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TPS62871N1QWRXSRQ1	TPS62872Y1QWRXSRQ1																											

Qualification Report
Automotive Qualification Summary
(As per AEC-Q100 Rev. J and JEDEC Guidelines)
Approve Date 14-July-2025

Product Attributes

Attributes	Qual Device: TPS62871Z0WRXSR	QBS Wafer fab Process Reference for group B TPS628502QDRLRQ1	QBS Package Reference for group A: LMQ66430MC3RXBRQ1	QBS Package Reference for group A: TPS61381QRAVRQ1	Original product Qualification TPS62870QWRXSRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Power Management	Power Management	Power Management	Power Management	Power Management
Wafer Fab Supplier	RFAB	RFAB	RFAB	RFAB	RFAB
Assembly Site	CLARK-AT	PHI	CLARK-AT	CLARK-AT	CARZ
Package Group	QFN	SOT	QFN	QFN	QFN
Package Designator	RXS	DRL	RXB	RAV	RXS
Pin Count	16	8	14	17	16

QBS: Qual By Similarity, also known as Generic Data
Qual Device TPS62871Z0WRXSR is qualified at MSL2 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: TPS62871Z0WRXSR	QBS Wafer fab Process Reference for group B TPS628502QDRLRQ1	QBS Package Reference for group A: LMQ66430MC3RXBRQ1	QBS Package Reference for group A: TPS61381QR AVRQ1	Original product Qualification TPS62870QWRXSRQ1
Test Group A - Accelerated Environment Stress Tests												
PC	A1	JEDEC J-STD-020 JEDEC22-A113	3	77	Preconditioning	MSL2 260C	-	1/77/0 and QBS		3/0/0	3/0/0	3/363/0
HAST	A2	JEDEC JEDEC22-A110	3	77	Biased HAST	110C/85%RH	264 Hours	QBS		3/231/0	-	-
HAST	A2	JEDEC JEDEC22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	QBS		-	3/231/0	1/77/0
AC/UHAST	A3	JEDEC JEDEC22-A102/JEDEC JEDEC22-A118	3	77	Unbiased HAST	110C/85%RH	264 Hours	QBS		3/231/0	-	-
AC/UHAST	A3	JEDEC JEDEC22-A102/JEDEC JEDEC22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	QBS		-	3/231/0	3/231/0
TC	A4	JEDEC JEDEC22-A104 and Appendix 3	3	77	Temperature Cycle	-55C/150C	1000 Cycles	1/77/0 and QBS			3/231/0	-
TC	A4	JEDEC JEDEC22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles			3/231/0	-	3/231/0
HTSL	A6	JEDEC JEDEC22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-QBS		3/135/0	1/45/0	3/135/0
Test Group B - Accelerated Lifetime Simulation Tests												
HTOL	B1	JEDEC JEDEC22-A108	3	77	Life Test	125C	1000 Hours	QBS and original device qual	3/231/0			1/77/0
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	QBS	3/2400/0			
Test Group C - Package Assembly Integrity Tests												
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	Generic family data		1/15/0	1/15/0	
PD	C4	JEDEC JEDEC22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	3/30/0				
Test Group D - Die Fabrication Reliability Tests												
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements				
TDBB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements				
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements				
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements				
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements				
Test Group E - Electrical Verification Tests												
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	Device specific data of original qualification				1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	750 Volts	Device specific data of original qualification				1/3/0
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	Device specific data of original qualification				1/6/0
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	Device specific data of original qualification				3/90/0
Additional Tests												
BLR	T1	-	-	-	Board Level Reliability - Temp Cycle	-40/125C	1000 Cycles	1/32/0				1/32/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C
Grade 1 (or Q): -40C to +125C
Grade 2 (or T): -40C to +105C
Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
TI Qualification ID: R-CHG-2409-093

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

ZVEI ID: SEM-PA-18, SEM-PA-11, SEM-TF-01

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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